

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	2029	(plurality) near3 (conductive near trace\$1)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 19:57
2	BRS	L2	107	(plurality) near3 (conductive near trace\$1 near layer)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 19:57
3	BRS	L3	53	((plurality) near3 (conductive near trace\$1 near layer)) near25 (via or hole)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
4	BRS	L4	15	((plurality) near3 (conductive near trace\$1)) near25 (via or hole) near15 (metal)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:36
5	BRS	L5	0	((plurality) near3 (conductive near trace\$1)) near25 (via or hole) near15 (sidewall or spacer)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:37
6	BRS	L6	0	((plurality) near3 (conductive near trace\$1)) near25 (via or hole) near15 (side- wall)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:37

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	1	((plurality) near3 (conductive near trace\$1)) near25 (via or hole) near15 (side near wall)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:38
8	BRS	L8	12	((conductive near trace\$1)) near25 (via or hole) near15 (side near wall)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:43
9	BRS	L9	31	((conductive near trace\$1)) near25 (via or hole) near15 (sidewall)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
10	BRS	L10	0	((conductive near trace\$1)) near25 (via or hole) near15 (side- wall)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:58
11	BRS	L11	33554	(isolat\$3) near15 (metal or copper)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:59
12	BRS	L12	3484	(insulat\$3) near10 (isolat\$3) near15 (metal or copper)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 20:59

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L13	269	(insulat\$3) near10 (via or hole) near10 (isolat\$3) near15 (metal or copper)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 21:00
14	BRS	L14	166	(insulat\$3) near10 (via) near10 (isolat\$3) near15 (metal or copper)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 21:05
15	BRS	L15	168	(insulat\$3) near10 (hole) near10 (isolat\$3) near15 (metal or copper)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/1 8 21:05

	U	1	Document ID	Title	Current OR
1			US 20040154907 A1	Electrical switch assembly	200/11R
2			US 20040113251 A1	Semiconductor chip package with a package substrate and a lid cover	257/684
3			US 20040112730 A1	Electrical switch assembly	200/284
4			US 20040056365 A1	Flip-chip image sensor packages and methods of fabrication	257/778
5			US 20040041282 A1	Flip-chip image sensor packages and methods of fabrication	257/796
6			US 20040041261 A1	FLIP-CHIP IMAGE SENSOR PACKAGES AND METHODS OF FABRICATION	257/737
7			US 20040041247 A1	Flip-chip image sensor packages and methods of fabrication	257/678
8			US 20030091208 A1	MICROPHONE WITH A VARIABLE RESISTANCE SWITCH	381/355
9			US 6597796 B2	Microphone with a variable resistance switch	381/361
10			US 5461196 A	Low temperature co-fired ceramic (LTCC) high density interconnect package with circuitry within the cavity walls	174/52.4

	U	1	Document ID	Title	Current OR
11			US 4230385 A	Printed circuit board, electrical connector and method of assembly	439/78
12			US 4216576 A	Printed circuit board, electrical connector and method of assembly	29/845